



AP Systems Investor Relations 2026



CREATING VALUE THROUGH TECHNOLOGIES



Contents

- I. Company Introduction
- II. The New AP Systems
- III. Financials
- IV. Business Detail



I. Company Introduction

- Company Overview
- Growth History
- Global Network and Facilities
- Major Customers

Company Overview

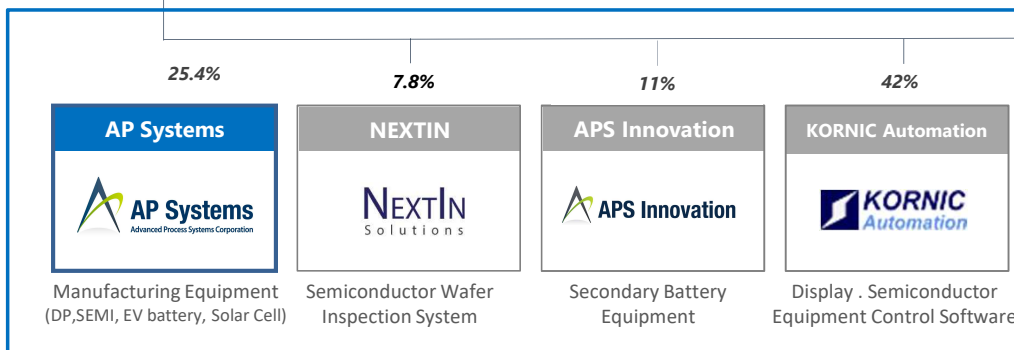


Corporate Structure



Founder : Ki Ro Jung
 former researcher of Electronics and Telecommunication Research Institute
 owns 35.4% shares of APS

KOSDAQ Listed Company



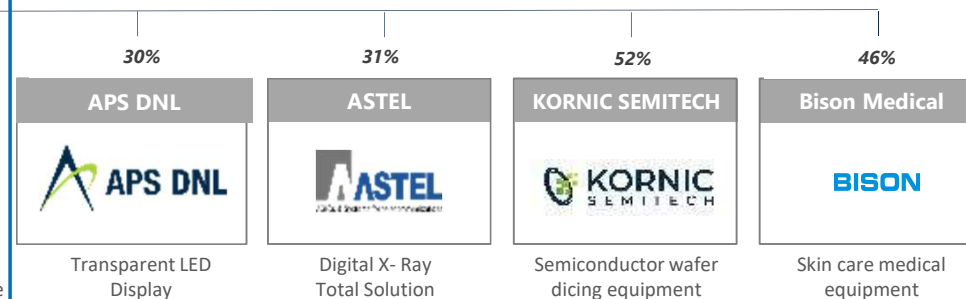
KOSDAQ Listed Company

Organization



CEO : Yoo Ho Sun

- Established in 1994
 - Paid in capital : KRW 7.6 billion
 - No. of Employees : 550
- Locations: Headquarters: South Korea (Dongtan)
 Fab: South Korea (Dongtan, Balan, Cheonan)
 Overseas: China (Shanghai), Vietnam (Hanoi), USA (Georgia)

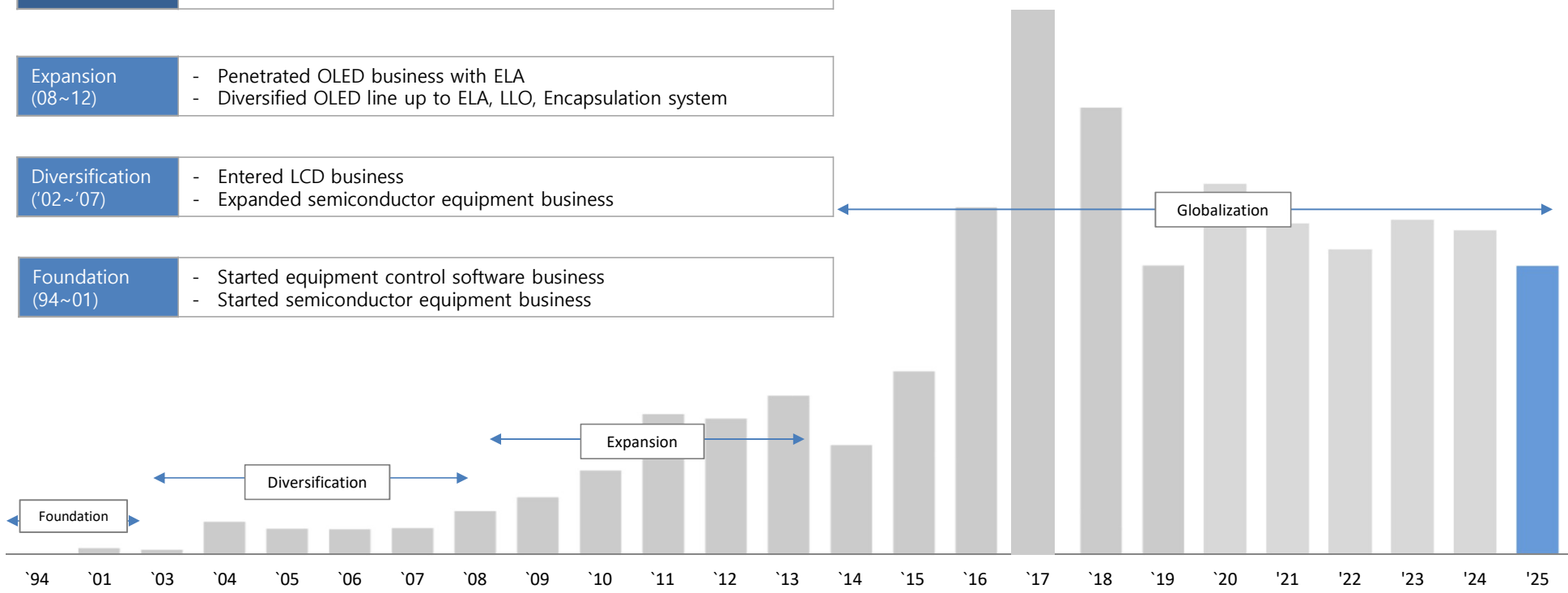


*AP Systems has 10.6% shares of DE&T Co.,Ltd and 9.3% of NEXTIN Inc.

Growth History



- Globalization ('13~present)**
 - Launched business to oversea market
 - Dominant presence of ELA(100% M/S excluding LGD)
 - Started back-end equipment business
 - Growing presence of Lamination
 - Penetrated DRAM business with RTP
- Expansion (08~12)**
 - Penetrated OLED business with ELA
 - Diversified OLED line up to ELA, LLO, Encapsulation system
- Diversification ('02~'07)**
 - Entered LCD business
 - Expanded semiconductor equipment business
- Foundation (94~01)**
 - Started equipment control software business
 - Started semiconductor equipment business



* Chart : Annual revenue

Global Network and Facilities



- Headquarters
- CS Center

APS China

Est. 2013
> Shanghai Office
> CS Centers

APS Vietnam

Est. 2016
> Hanoi Office
> CS Centers

APSYSTEMS AMERICA

Est. 2024
> Georgia Office
> CS Centers

Total Clean Room : 30,000m²



FAB 1 (Dongtan)

Clean Room: 5,200m²



FAB 2 (Dongtan2)

Clean Room: 4,800m²



FAB 3 (Cheonan)

Clean Room: 17,200m²



FAB 4 (Baran)

Clean Room: 2,800m²

❖ Total CAPEX capable of generating sales of \$1B

Major Customers

Semiconductor

Display

Renewable Energy



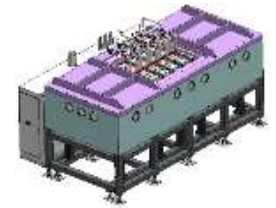
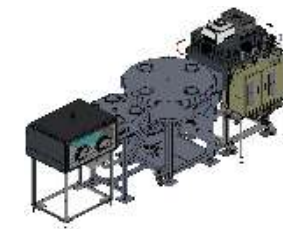
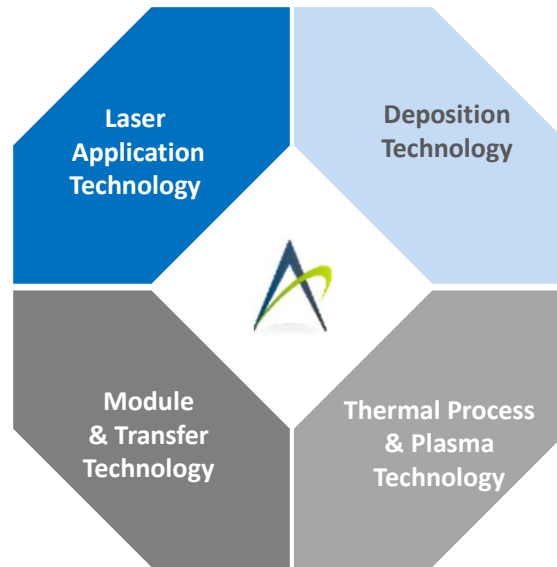
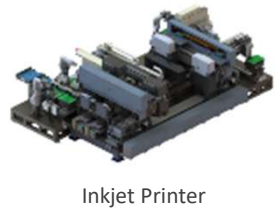
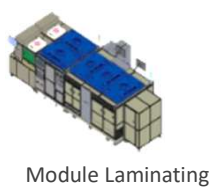
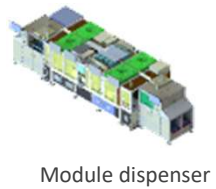
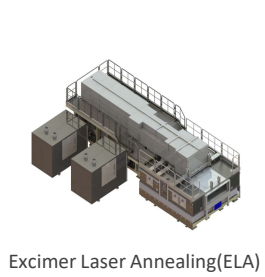




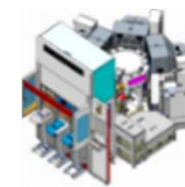
II. The New AP Systems

- Core Technologies
- Business & Products
- The Next Step

Core Technologies



Atomic Layer Deposition(ALD)



Rapid Thermal Process(RTP)

Sputter

Business & Products



SEMICONDUCTOR

Front-end



Rapid Thermal Process(RTP)

Back-end



Sputter



Laser Dicing



Laser De-bonder

OLED

Front-end



Excimer Laser Annealing(ELA)



Laser Lift-Off(LLO)



Encapsulation

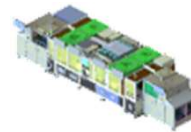


Atomic Layer Deposition(ALD)

Back-end



Module Laminating

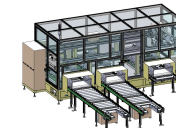


Module dispenser



Inkjet Printer

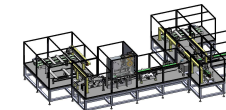
EV BATTERY



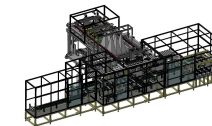
NG Sorter



Tray Washer



Cell Taping

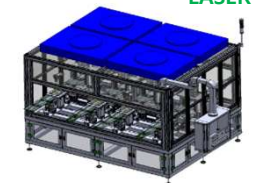


Cell Packing

SOLAR CELL

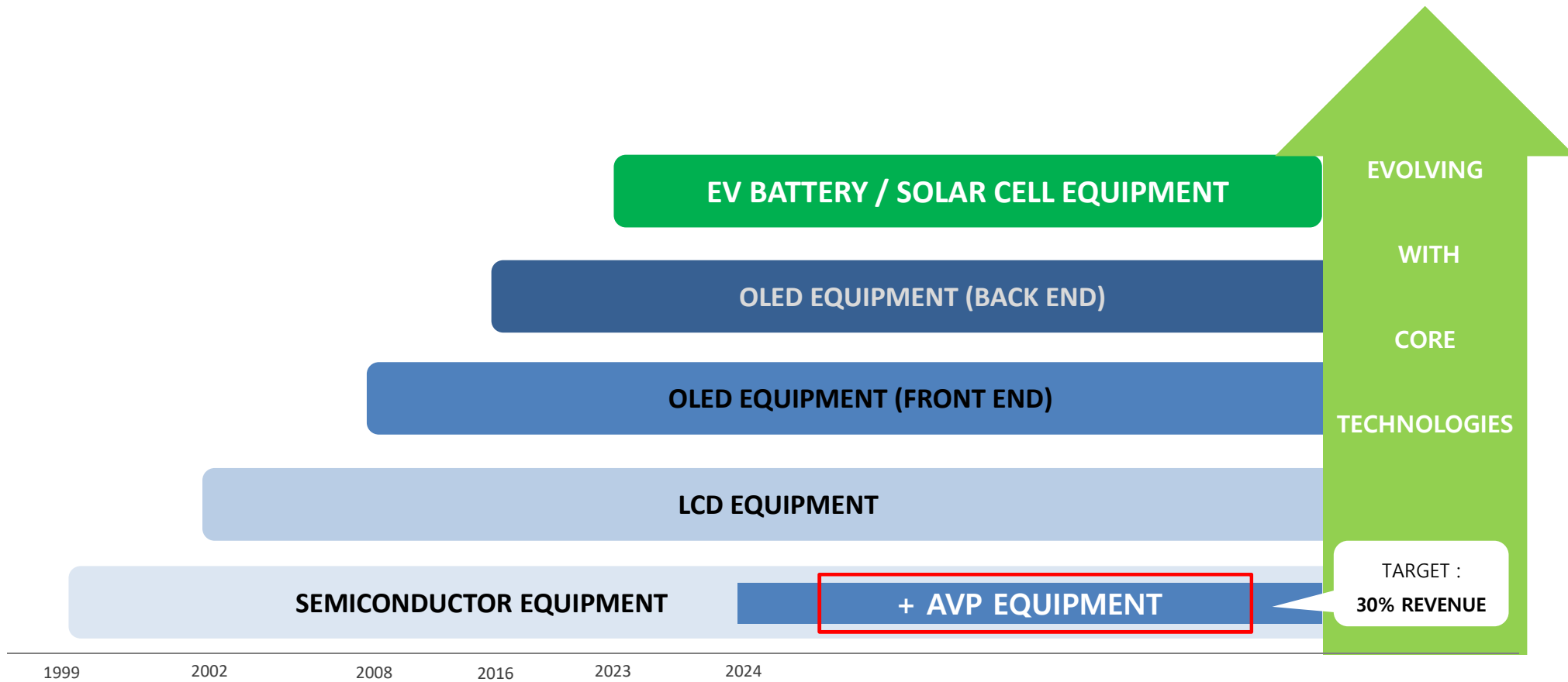


Laser Edge Isolation (LEI)



Laser Doped Selective Emitters(LDSE)

The Next Step





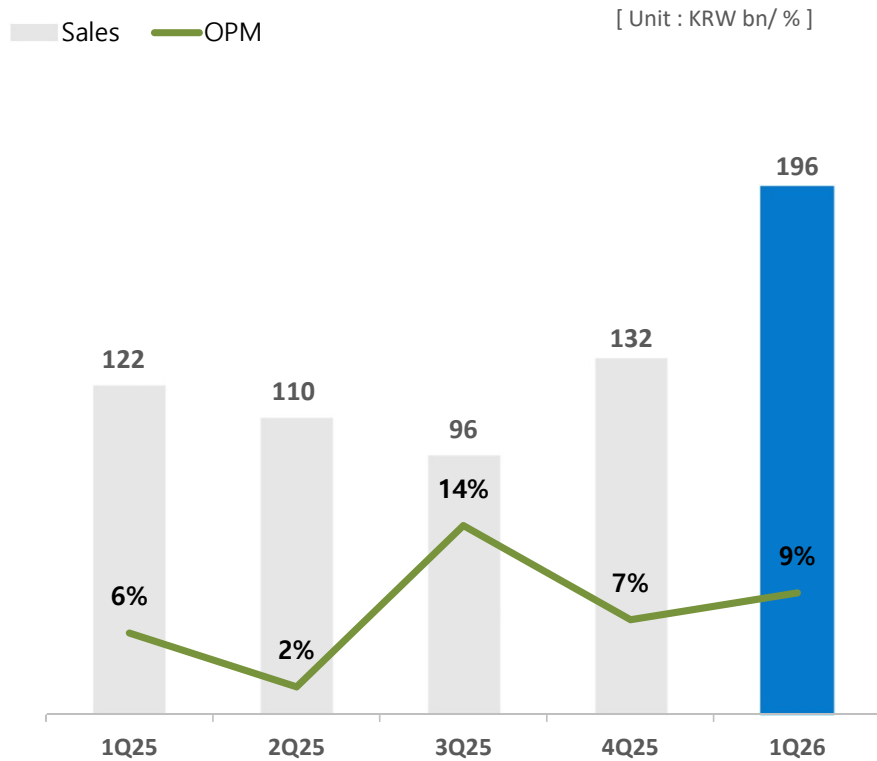
III. Financials

- Business Results : 1Q26
- Consolidated Financial Statements

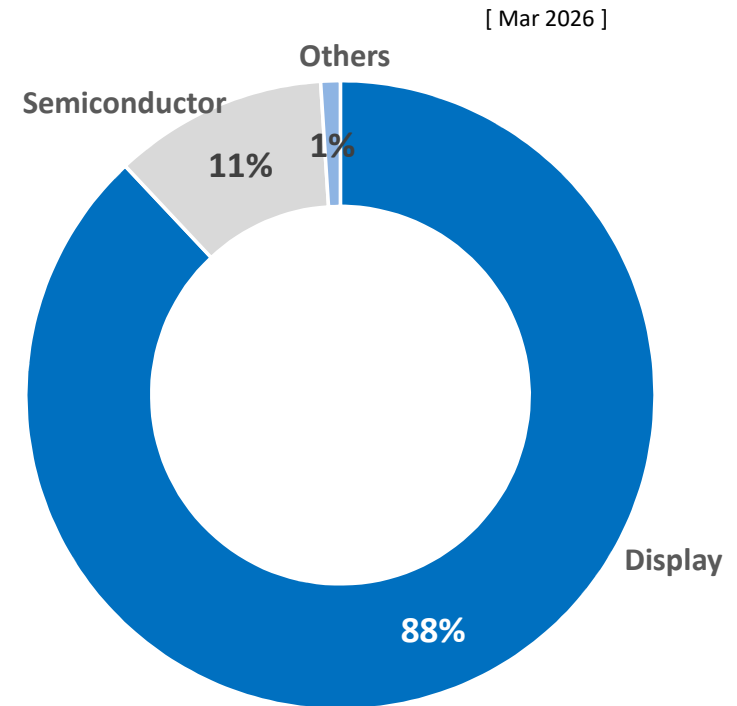
Business Results : 1Q26



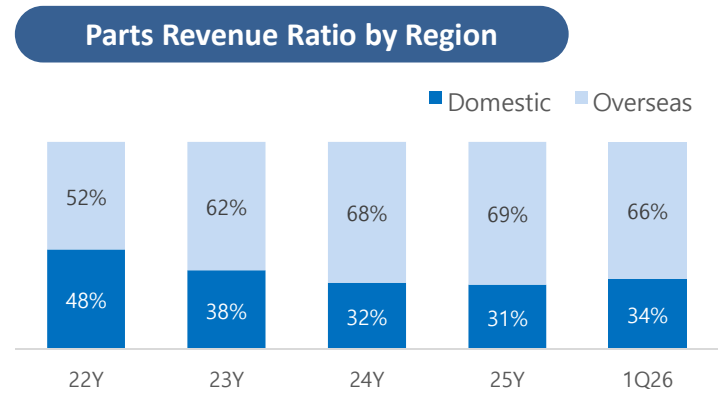
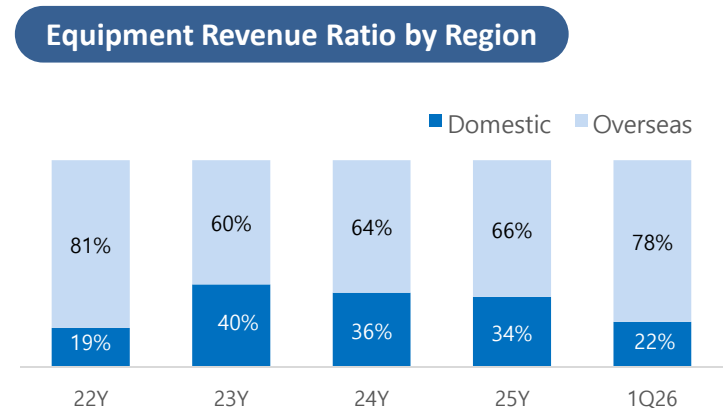
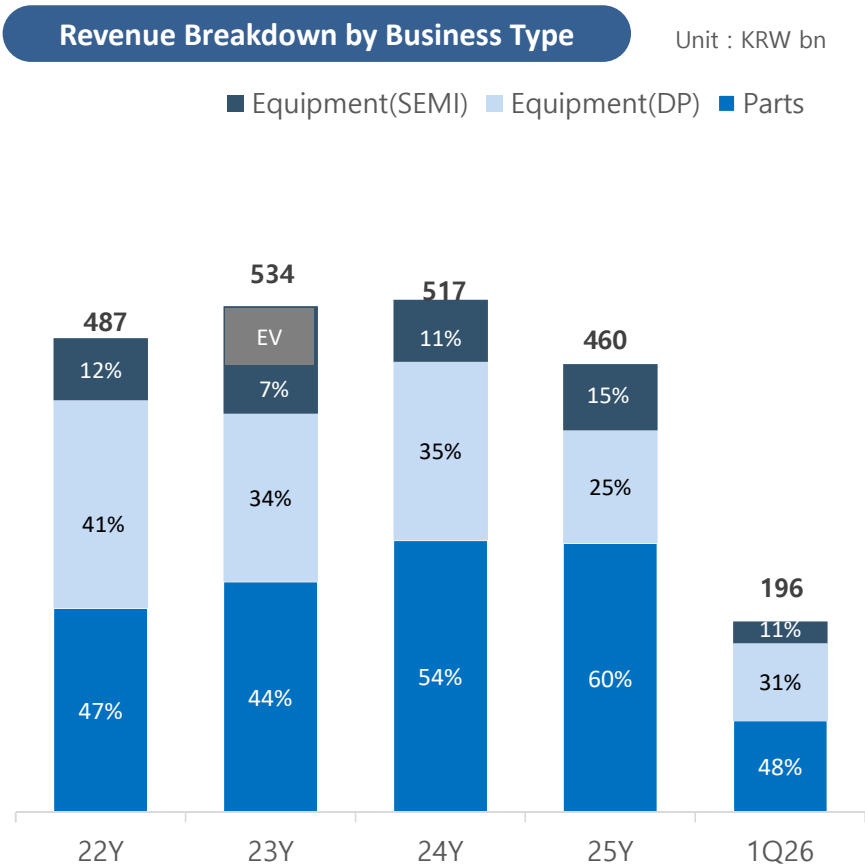
Quarterly Revenue



Revenue Breakdown by Division



Business Results : 1Q26



Consolidated Financial Statements



Balance Sheet Summary

[Unit : KRW bn]	1Q26	2025	2024	2023	2022
Current Assets	427	411	376	390	396
Non-current Assets	260	270	224	181	152
Total Assets	687	681	600	571	548
Current Liabilities	241	224	197	174	222
Non-current Liabilities	72	89	66	76	55
Total Liabilities	314	313	263	250	277
Current Ratio (%)	177%	184%	191%	225%	178%
Debt Ratio (%)	84%	85%	78%	78%	103%
Total Capital	373	368	337	321	270

Income Statement Summary

[Unit : KRW bn]	1Q26	2025	2024	2023	2022
Revenue	196	460	517	534	487
Gross Profits	32	89	100	106	142
General Expenses	14	56	53	46	52
Operating Profits	18	33	47	60	90
OP Margin(%)	9.2%	7.2%	9.1%	11.2%	18.6%
Profits before Tax	26	27	66	76	111
Net Profits	20	24	52	60	82

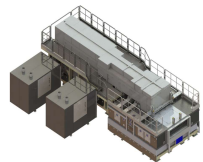
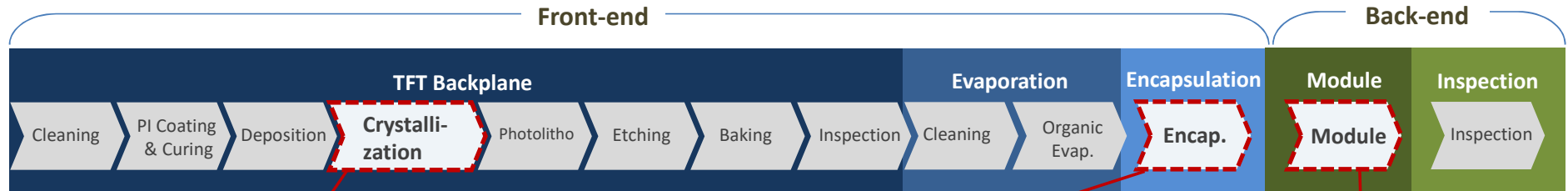
* Cumulative total



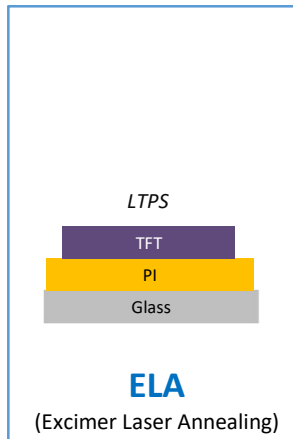
IV. Business Detail

- Display(OLED)
- Semiconductor

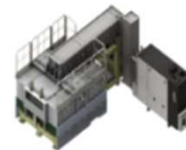
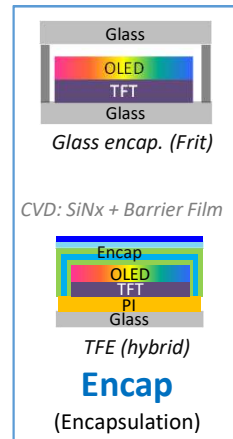
Product Line-up for Display(OLED)



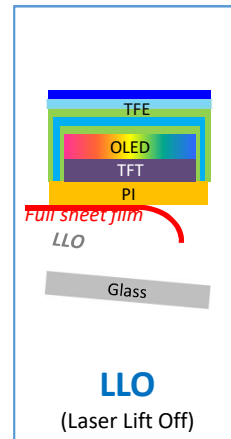
Excimer Laser Annealing



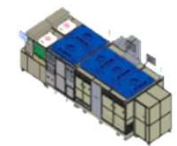
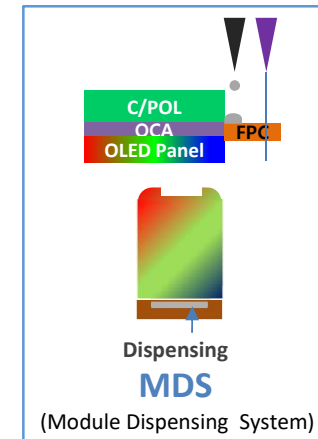
Encapsulation



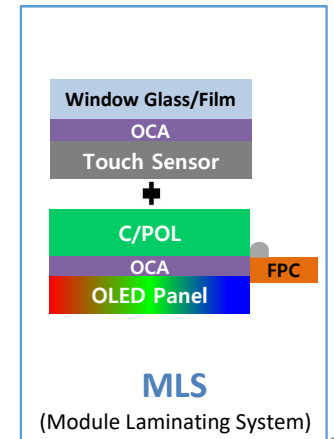
Laser Lift-Off



Module Dispensing



Module Laminating



Highlights : OLED

NOW



FRONT
END

ELA, LLO, Encapsulation

BACK
END

Laminating, Dispensing

More Demand



New Investment

&

Equipment / Parts ↑

FUTURE

Increase of OLED applications



ELA, LLO, Encapsulation + ALD

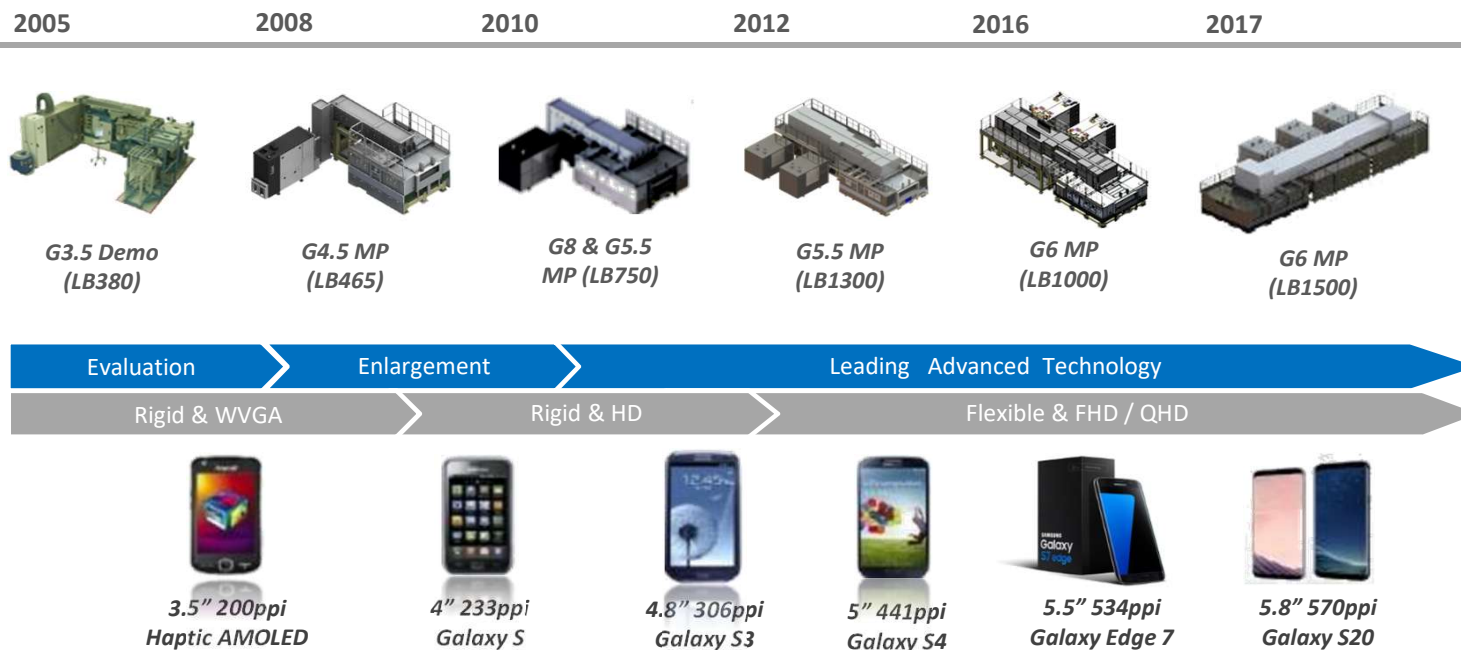
Laminating, Dispensing + OCR Inkjet Printer

Signature Equipment

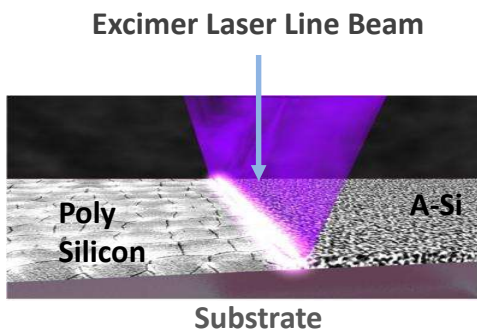
ELA (Excimer Laser Annealing)



AP Products



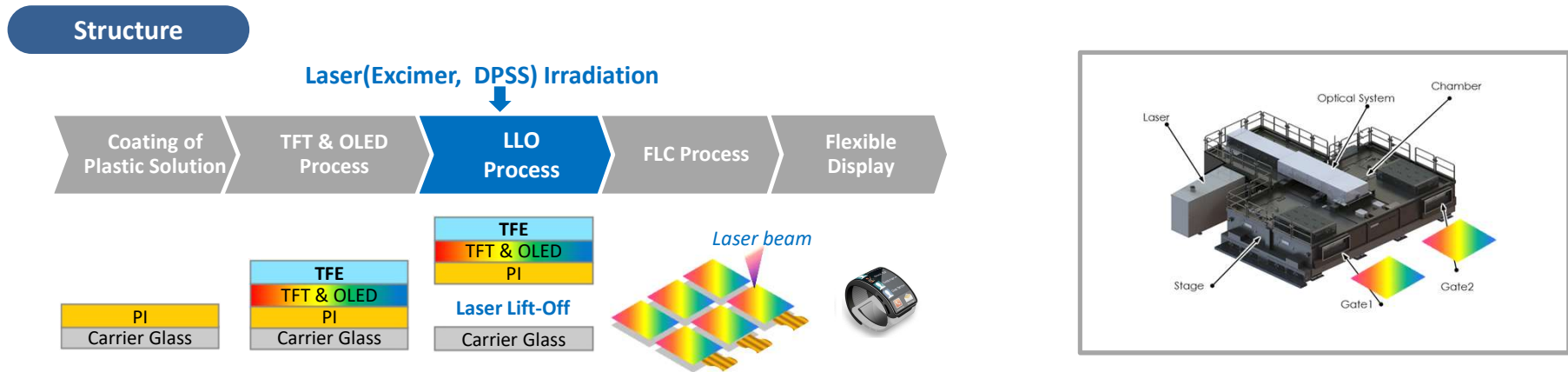
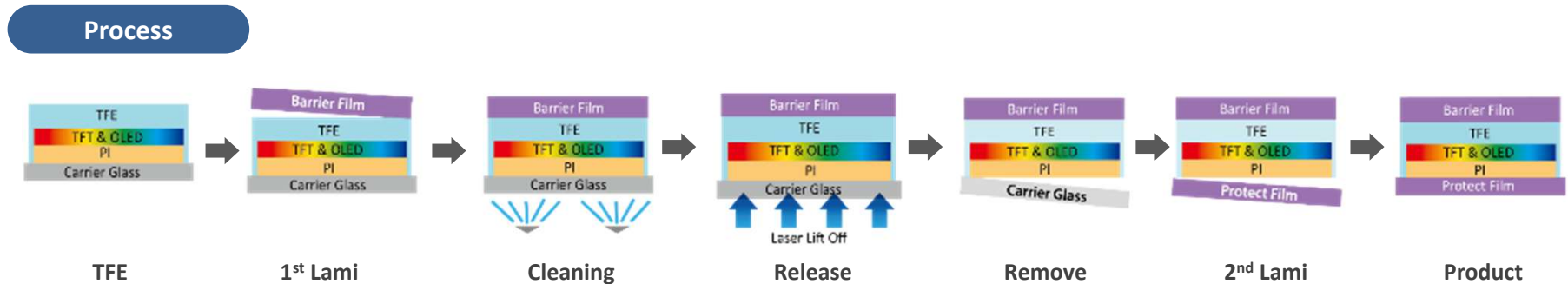
Customer Products



**More than 12 years experience in AMOLED*

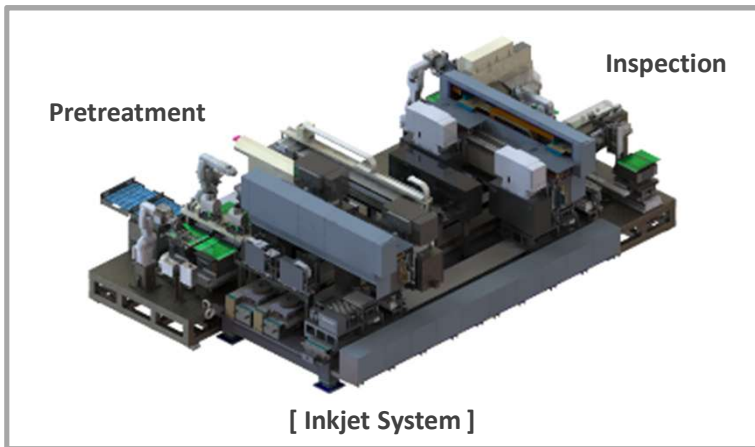
Signature Equipment

LLO (Laser Lift-Off)

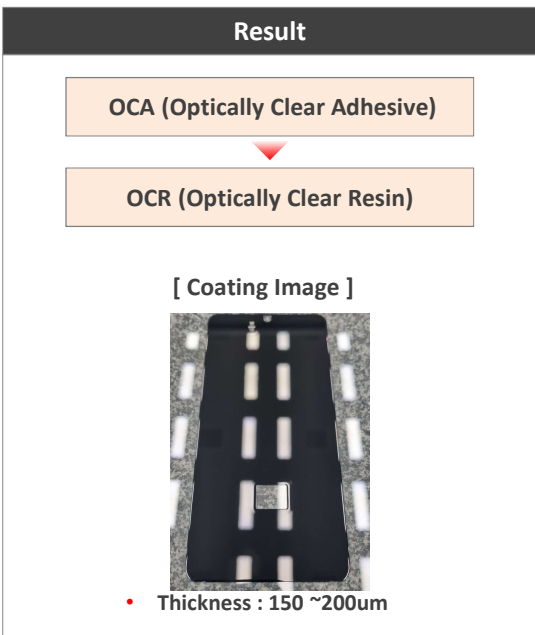
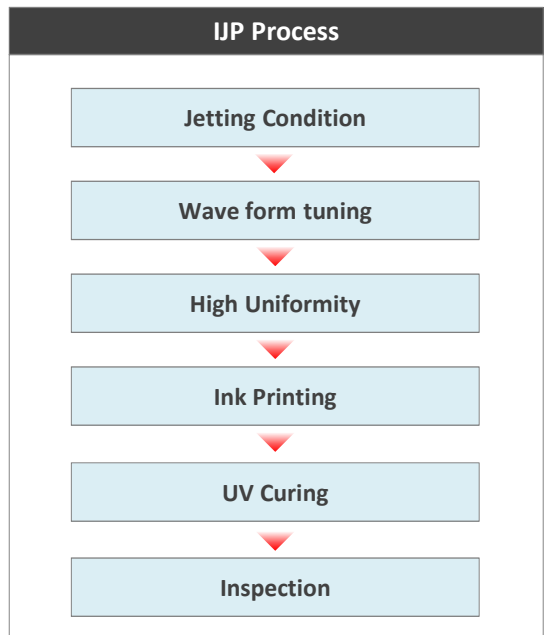


New Equipment

Module OCR IJP(Inkjet Printer)

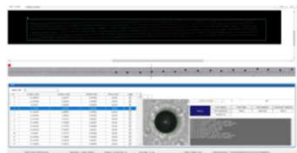


Technology



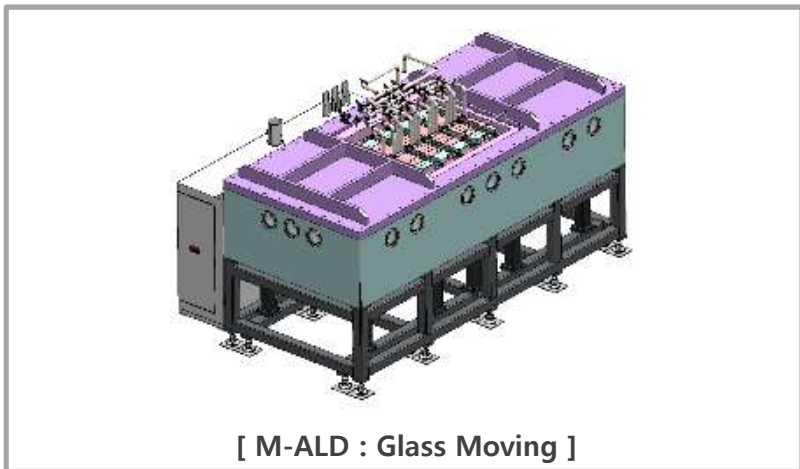
Advantage of APS' IJP

- High Performance Printing
- Easy User Interface
- Inspection : 2D , 3D , AOI
- Compact Equipment
- Best Maintenance



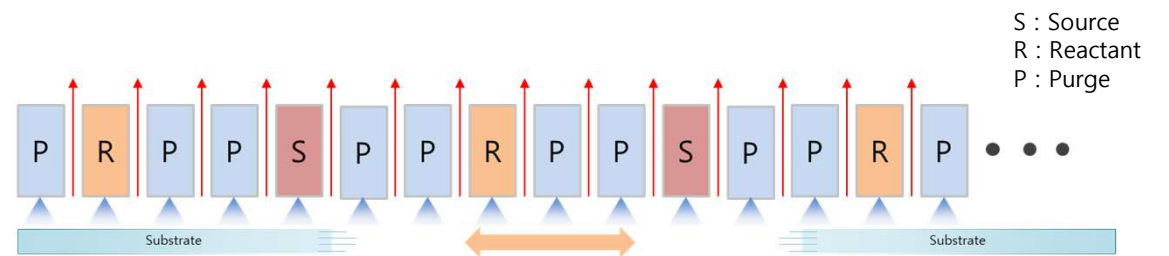
New Equipment

PEALD (Plasma Enhanced Atomic Layer Deposition) : M-type For 8.5G IT OLED



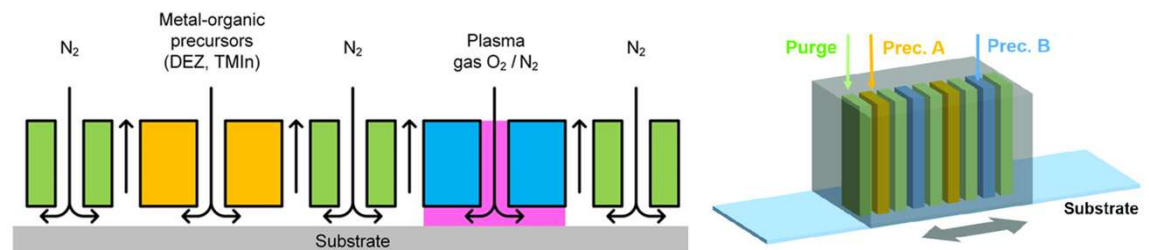
Technology

Rapid Deposition with Multiple linear nozzle & Glass moving



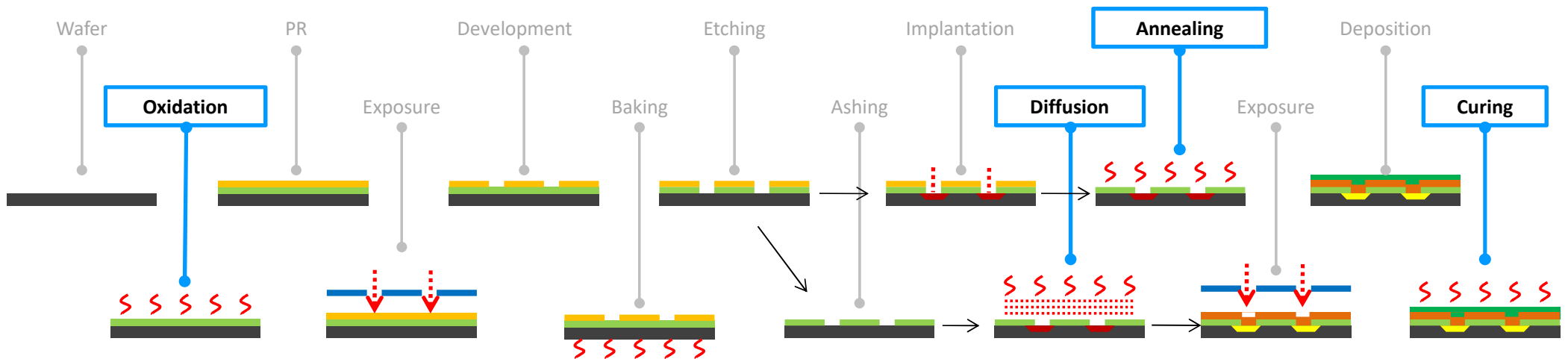
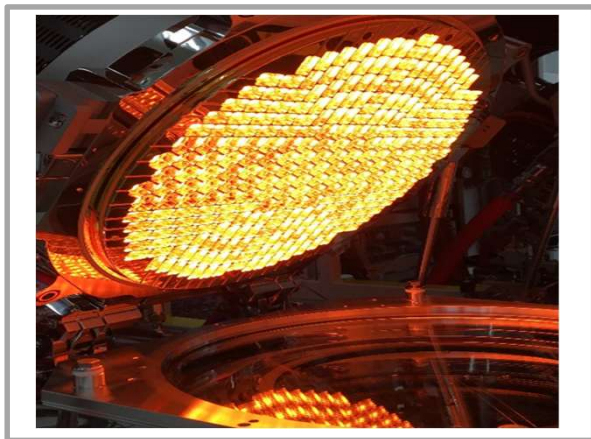
Space Divided ALD for Oxide TFT(IGZO)

- High deposition rate than Conventional ALD
→ Dep. Rate > 40Å/min
- Spatial separation of reaction, instead of time one
→ No intermixing of precursor and reactant



Signature Equipment

RTP (Rapid Thermal Process)





Thank you

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